

Triple Analog Video Delay Line

The EL9115 is a triple analog delay line that allows skew compensation between any three signals. This part is perfect for compensating for the skew introduced by a typical CAT-5 cable with differing electrical lengths on each pair.

The EL9115 can be programmed in steps of 2ns up to 62ns total delay on each channel.

Ordering Information

| PART NUMBER | PART MARKING | PACKAGE | PKG. DWG. # |
|-----------------------|--------------|-----------------------------|-------------|
| EL9115IL | 9115IL | 20 Ld 5mmx5mm QFN | L20.5x5C |
| EL9115ILZ (Note) | 9115ILZ | 20 Ld 5mmx5mm QFN (Pb-free) | L20.5x5C |
| EL9115ILZ-T7* (Note) | 9115ILZ | 20 Ld 5mmx5mm QFN (Pb-free) | L20.5x5C |
| EL9115ILZ-T13* (Note) | 9115ILZ | 20 Ld 5mmx5mm QFN (Pb-free) | L20.5x5C |

*Please refer to TB347 for details on reel specifications.

NOTE: These Intersil Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

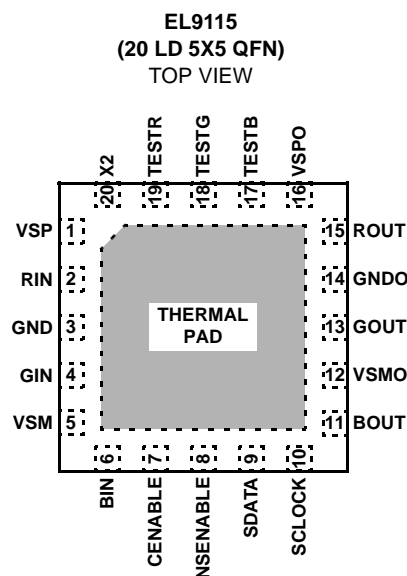
Features

- 62ns total delay
- 2ns delay step increments
- Operates from $\pm 5V$ supply
- Up to 122MHz bandwidth
- Low power consumption
- 20 Ld QFN (5mmx5mm) package
- Pb-free available (RoHS compliant)

Applications

- Skew control for RGB
- Analog beamforming

Pinout



EXPOSED DIEPLATE SHOULD BE CONNECTED TO -5V

Absolute Maximum Ratings ($T_A = +25^\circ\text{C}$)

Supply Voltage (V_{S+} to V_{S-})12V
 Maximum Output Current $\pm 60\text{mA}$
 Storage Temperature Range -65°C to $+150^\circ\text{C}$

Thermal Information

Power Dissipation See Curves
 Pb-Free Reflow Profile see link below
<http://www.intersil.com/pbfree/Pb-FreeReflow.asp>

Operating Conditions

Operating Junction Temperature $+135^\circ\text{C}$
 Ambient Operating Temperature -40°C to $+85^\circ\text{C}$

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

IMPORTANT NOTE: All parameters having Min/Max specifications are guaranteed. Typical values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: $T_J = T_C = T_A$

DC Electrical Specifications $V_{SA+} = V_{A+} = +5\text{V}$, $V_{SA-} = V_{A-} = -5\text{V}$, $T_A = +25^\circ\text{C}$, exposed die plate = -5V , unless otherwise specified.

| PARAMETER | DESCRIPTION | CONDITION | MIN | TYP | MAX | UNIT |
|---------------------|---------------------------------|--|-------|-------|------|---------------|
| V+ | Positive Supply Range | | +4.5 | | +5.5 | V |
| V- | Negative Supply Range | | -4.5 | | -5.5 | V |
| G_0 | Gain Zero Delay | X2 = 5V, 150 Ω load | 1.81 | 1.89 | 2.04 | |
| G_m | Gain Mid Delay | | 1.66 | 1.84 | 2.04 | |
| G_f | Gain Full Delay | | 1.52 | 1.79 | 2.04 | |
| DG_m0 | Difference in Gain, 0 to Mid | | -7.5 | -2.5 | 2.5 | % |
| DG_f0 | Difference in Gain, 0 to Full | | -13.5 | -6.0 | 2.5 | % |
| DG_fm | Difference in Gain, Mid to Full | | -10.0 | -2.6 | 4.0 | % |
| V _{IN} | Input Voltage Range | Gain falls to 90% of nominal | -0.7 | | 1.3 | V |
| I _B | Input Bias Current | | | 1 | 5 | μA |
| R _{IN} | Input Resistance | | | 10 | | M Ω |
| V _{OS_0} | Output Offset 0 Delay | X2 = +5V, 75 + 75 Ω load | -200 | -150 | 60 | mV |
| V _{OS_M} | Output Offset Full Delay | | -200 | -140 | 60 | mV |
| V _{OS_F} | Output Offset Mid Delay | | -200 | -130 | 60 | mV |
| Z _{OUT} | Output Impedance | Chip enable = +5V | 4.5 | 5 | 6.3 | Ω |
| | | Chip enable = 0V | | 1 | | M Ω |
| +PSRR | Rejection of Positive Supply | X2 = +5V into 75 + 75 Ω load | | -38 | | dB |
| -PSRR | Rejection of Negative Supply | X2 = +5V into 75 + 75 Ω load | | -53 | | dB |
| I _{SP} | Supply Current (Note 1) | Chip enable = +5V current on V _{SP} | 75 | 87 | 115 | mA |
| I _{SM} | Supply Current (Note 1) | Chip enable = +5V current in V _{SM} | -10.5 | -8.6 | -7 | mA |
| I _{SMO} | Supply Current (Note 1) | Chip enable = +5V current in V _{SMO} | -13 | -11.6 | -10 | mA |
| I _{SPO} | Supply Current (Note 1) | Chip enable = +5V current in V _{SPO} | 10 | 11.8 | 15.5 | mA |
| ΔI_{SP} | Supply Current (Note 1) | Increase in I _{SP} per unit step in delay | | 0.9 | | mA |
| I _{SP OFF} | Supply Current (Note 1) | Chip enable = 0V current in V _{SP} | | 1.6 | | mA |
| I _{OUT} | Output Drive Current | 10 Ω load, 0.5V drive, X2 = 5V | 30 | | | mA |
| L _{HI} | Logic High | Switch high threshold | | 1.25 | 1.6 | V |
| L _{LO} | Logic Low | Switch low threshold | 0.8 | 1.15 | | V |

AC Electrical Specifications $V_{SA+} = V_{A+} = +5V$, $V_{SA-} = V_{A-} = -5V$, $T_A = +25^{\circ}C$, exposed die plate = -5V, unless otherwise specified.

| PARAMETER | DESCRIPTION | CONDITION | MIN | TYP | MAX | UNIT |
|--------------|--|---|------|-----|------|-------------------|
| BW -3dB | 3dB Bandwidth | 0ns Delay Time | | 122 | | MHz |
| BW 0.1dB | 0.1dB Bandwidth | 0ns Delay Time | | 60 | | MHz |
| SR | Slew Rate | 0ns Delay Time | | 400 | | V/ μ s |
| $t_R - t_F$ | Transient Response Time | 20% to 80%, for all delays, 1V step | | 2.5 | | ns |
| V_{OVER} | Voltage Overshoot | for any delay, response to 1V step input | | 5 | | % |
| Glitch | Switching Glitch | Time for o/p to settle after last s_clock edge | | 100 | | ns |
| THD | Total Harmonic Distortion | 1V _{P-P} 10MHz sinewave, offset by +0.2V at mid delay setting | | -50 | -40 | dB |
| X_t | Hostile Crosstalk | Stimulate G, measure R/B at 1MHz | | -80 | | dB |
| V_N | Output Noise | Gain X2, measured at 75 Ω load | | 2.5 | | mV _{RMS} |
| d_t | Nominal Delay Increment | Note 2 | 1.75 | 2 | 2.25 | ns |
| t_{MAX} | Maximum Delay | | 55 | 62 | 70 | ns |
| D_{ELDT} | Delay Diff Between Channels | | | 1.6 | | % |
| t_{PD} | Propagation Delay | Measured input to output | | 9.8 | | ns |
| t_{MAX} | Max s_clock Frequency | Maximum programming clock speed | | | 10 | MHz |
| t_{en_ck} | Minimum Separation Between Serial Enable and Clock | Check enable low edge can occur after t_{en_ck} of previous (ignored) clock and up to before t_{en_ck} of next (wanted) clock. Clock edges occurring within t_{en_ck} of the enable edge will have uncertain effect. | | 10 | | ns |

NOTES:

1. All supply currents measured with Delay R = 0ns, G = mid delay, B = full delay.
2. Delay increment limits are derived by taking Maximum Delay limits and dividing by the number of steps for the device (e.g. the number of steps for the EL9115 is 31).

Pin Descriptions

| PIN NUMBER | PIN NAME | PIN DESCRIPTION |
|------------|----------|---|
| 1 | VSP | +5V for delay circuitry and input amp |
| 2 | RIN | Red channel input, ref GND |
| 3 | GND | 0V for delay circuitry supply |
| 4 | GIN | Green channel input, ref GND |
| 5 | VSM | -5V for input amp |
| 6 | BIN | Blue channel input, ref GND |
| 7 | CENABLE | Chip enable logical +5V enables chip |
| 8 | NSENABLE | \overline{ENABLE} for serial input; enable on low |
| 9 | SDATA | Data into registers; logic threshold 1.2V |
| 10 | SCLOCK | Clock to enter data; logical; data written on negative edge |
| 11 | BOUT | Blue channel output, ref GND _O |
| 12 | VSMO | -5V for output buffers |
| 13 | GOUT | Green channel output, ref GND _O |
| 14 | GNDO | 0V reference for input and output buffers |
| 15 | ROUT | Red channel output, ref GND _O |
| 16 | VSP0 | +5V for output buffers |
| 17 | TESTB | Blue channel phase detector output |
| 18 | TESTG | Green channel phase detector output |

Pin Descriptions (Continued)

| PIN NUMBER | PIN NAME | PIN DESCRIPTION |
|-------------|----------|---|
| 19 | TESTR | Red channel phase detector output |
| 20 | X2 | Sets gain to 2X if input high; X1 otherwise |
| Thermal Pad | | Must be connected to -5V |

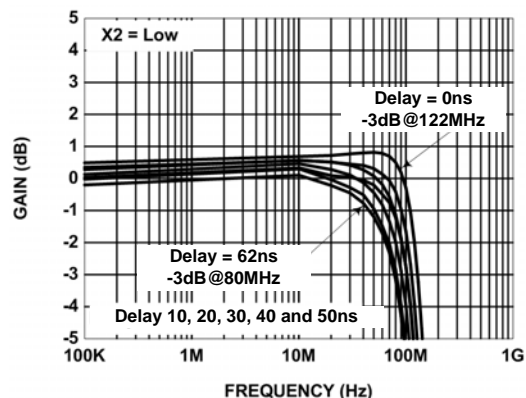
Typical Performance Curves

FIGURE 1. GAIN vs FREQUENCY

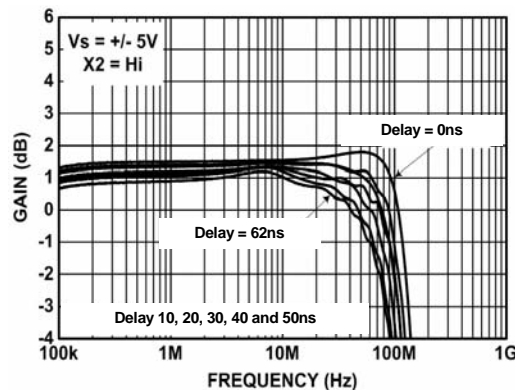


FIGURE 2. GAIN vs FREQUENCY

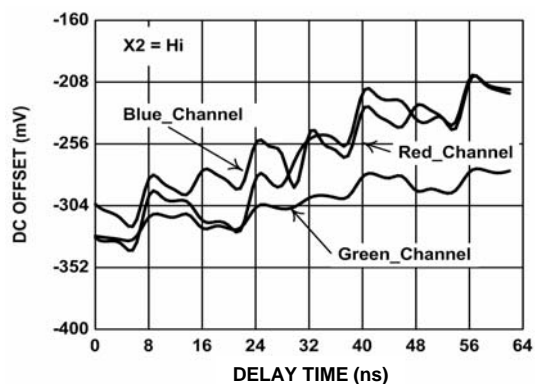


FIGURE 3. TYPICAL DC OFFSET vs DELAY TIME (X2 = Hi)

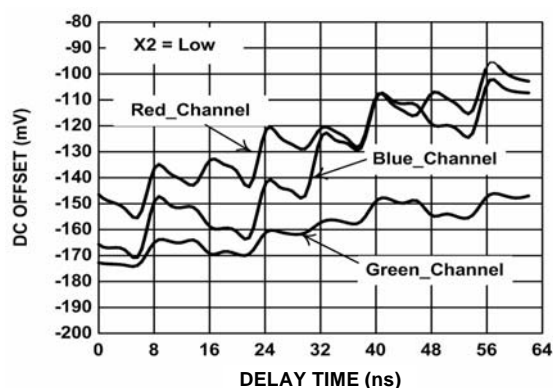


FIGURE 4. TYPICAL DC OFFSET vs DELAY TIME (X2 = Low)

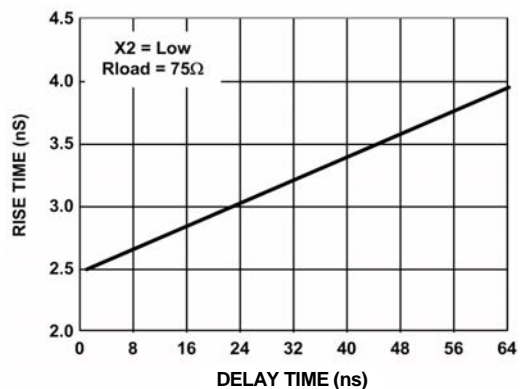


FIGURE 5. RISE TIME vs DELAY TIME

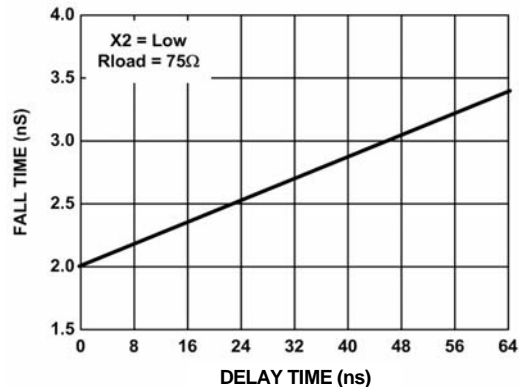


FIGURE 6. FALL TIME vs DELAY TIME

Typical Performance Curves (Continued)

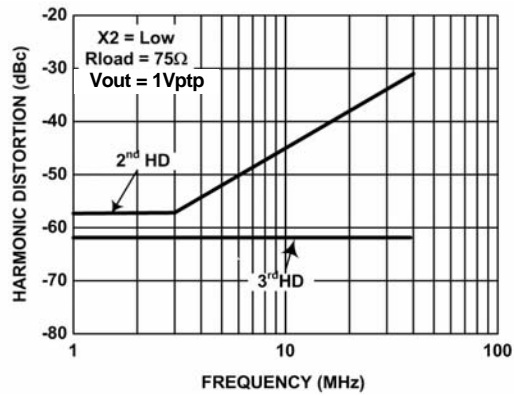


FIGURE 7. DISTORTION vs FREQUENCY

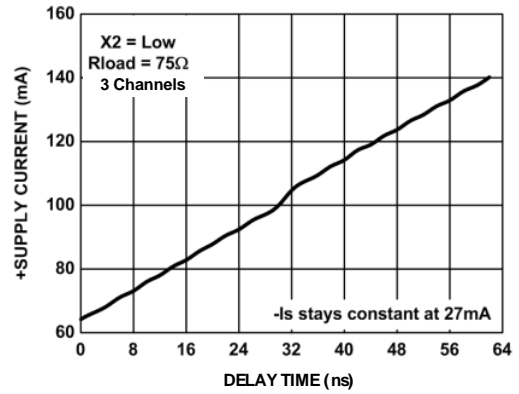


FIGURE 8. POSITIVE SUPPLY CURRENT vs DELAY TIME

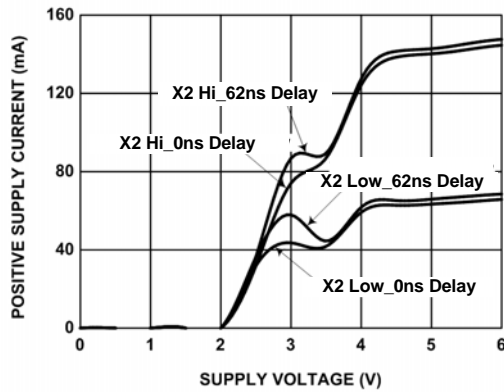


FIGURE 9. $I_{SUPPLY+}$ vs $V_{SUPPLY+}$

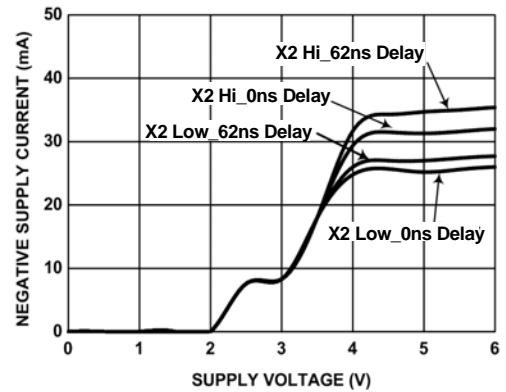


FIGURE 10. $I_{SUPPLY-}$ vs $V_{SUPPLY-}$

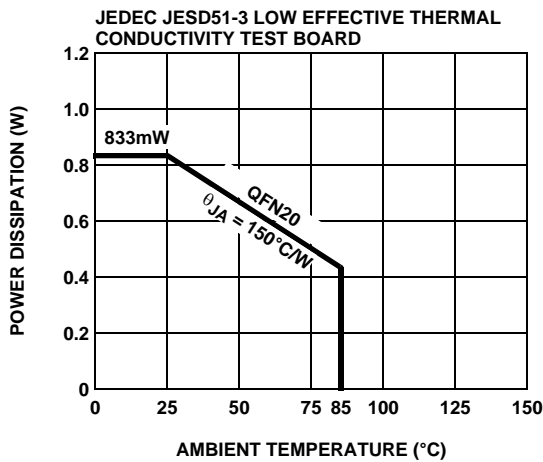


FIGURE 11. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

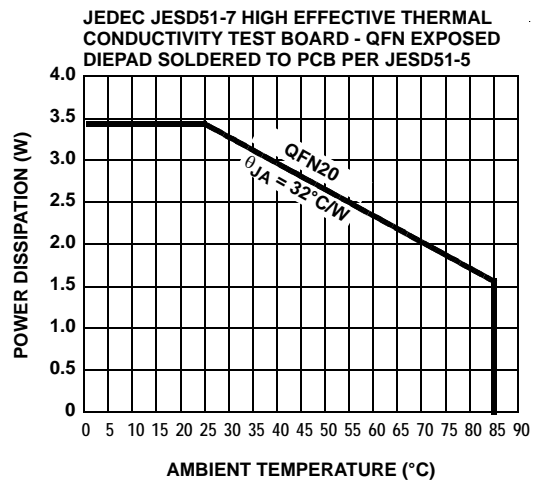


FIGURE 12. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

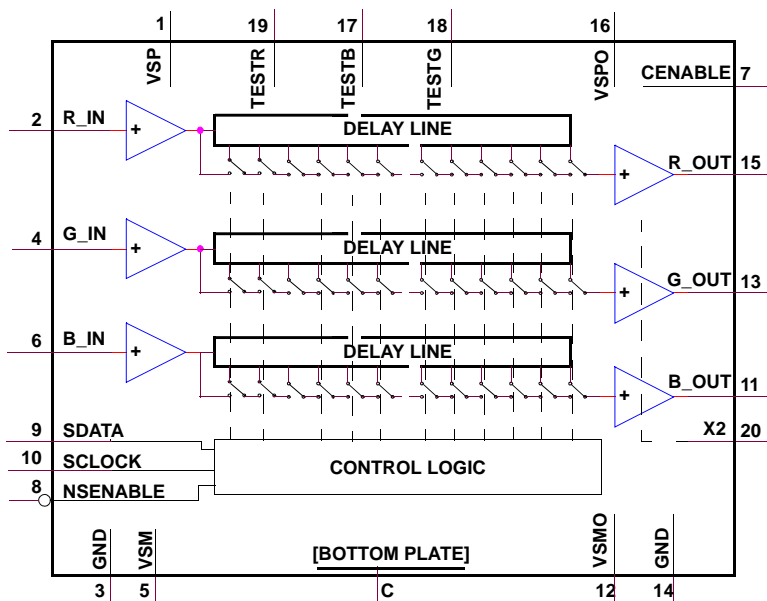


FIGURE 13. EL9115 BLOCK DIAGRAM

Applications Information

EL9115 is a triple analog delay line receiver that allows skew compensation between any three high frequency signals. This part compensates for time skew introduced by a typical CAT-5 cable with differing electrical lengths on each pair. The EL9115 can be independently programmed via SPI interface in steps of 2ns up to 62ns total delay on each channel while achieving over 80MHz bandwidth.

Figure 13 shows the EL9115 block diagram. The 3 analog inputs are ground reference single-ended signals. After the signal is received, the delay is introduced by switching filter blocks into the signal path. Each filter block is an all-pass filter introducing 2ns delay. In addition to time delay, each filter block also introduces some low pass filtering. As a result, the bandwidth of the signal path decreases from 120MHz at 0ns delay setting to 80MHz at the maximum delay setting, as shown in Figure 1 of the "Typical Performance Curves" on page 4.

In addition to delay, the extra amplifiers in the signal path also introduce offset voltage. The output offset voltage can shift by 100mV for X2 high setting and 50mV for X2 low.

In operation, it is best to allocate the most delayed signal 0ns delay then increase the delay on the other channels to bring them into line. This will result in the lowest power and distortion solution to balancing delays.

Power Dissipation

As the delay setting increases, additional filter blocks turn on and insert into the signal path. For each 2ns of delay per channel, V_{SP} current increases by 0.9mA while V_{SM} does not change significantly. Under the extreme settings, the positive supply current reaches 140mA and the negative

supply current can be 35mA. Operating at $\pm 5V$ power supply, the total power dissipation is:

$$PD = 5 \cdot 140mA + 5 \cdot 35mA = 875mW \quad (EQ. 1)$$

θ_{JA} required for long term reliable operation can be calculated. This is done using Equation 2:

$$\theta_{JA} = (T_J - T_A) / PD = 57^\circ C/W \quad (EQ. 2)$$

Where:

T_J is the maximum junction temperature ($+135^\circ C$)

T_A is the maximum ambient temperature ($+85^\circ C$)

For a 20 Ld package in a proper layout PCB heatsinking copper area, $40^\circ C/W$ θ_{JA} thermal resistance can be achieved. To disperse the heat, the bottom heatspreader must be soldered to the PCB. Heat flows through the heatspreader to the circuit board copper then spreads and convects to air. Thus, the PCB copper plane becomes the heatsink (see TB389). This has proven to be a very effective technique. A separate application note, which details the 20 Ld QFN PCB design considerations, is available.

TABLE 1. SERIAL BUS DATA

| vwxyz | DELAY |
|-------|-------|
| 00000 | 0 |
| 00001 | 2 |
| 00010 | 4 |
| 00011 | 6 |
| 00100 | 8 |
| 00101 | 10 |
| 00110 | 12 |

TABLE 1. SERIAL BUS DATA (Continued)

| vwxyz | DELAY |
|-------|-------|
| 00111 | 14 |
| 01000 | 16 |
| 01001 | 18 |
| 01010 | 20 |
| 01011 | 22 |
| 01100 | 24 |
| 01101 | 26 |
| 01110 | 28 |
| 01111 | 30 |
| 10000 | 32 |
| 10001 | 34 |
| 10010 | 36 |
| 10011 | 38 |
| 10100 | 40 |
| 10101 | 42 |
| 10110 | 44 |
| 10111 | 46 |
| 11000 | 48 |
| 11001 | 50 |
| 11010 | 52 |
| 11011 | 54 |
| 11100 | 56 |
| 11101 | 58 |
| 11110 | 60 |
| 11111 | 62 |

NOTE: Delay register word = 0abvwxyz; Red register - ab = 01;
Green register - ab = 10; Blue register - ab = 11; vwxyz selects delay.

Serial Bus Operation

On the first negative clock edge after NSEnable goes low, read the input from DATA. This DATA level should be 0 (write into registers); READ is not supported. Read the next two data bits on subsequent negative edges and interpret them as the register to be filled. Reg 01 = R, 02 = G, 03 = B, 00 test use. Read the next five bits of data and send them to register. At the end of each block of 8 bits, any further data is treated as being a new word. Data entered is shifted directly to the final registers as it is clocked in. Initial value of all registers on power-up is 0. It is the user's responsibility to send complete patterns of 8 clock cycles, even if the first bit is set to 1. If less than 8 bits are sent, data will only be partially shifted through the registers. The pattern of 8 starts with NSEnable going low, so it is good practice to frame each word within an NS enable burst.

Test Pins

Three test pins are provided (Test R, Test G, Test B). During normal operation, the test pins output pulses of current for a duration of the overlap between the inputs, as shown in Figure 15:

Test_R pulse = Red out (A) wrt Green out (B)

Test_G pulse = Green out wrt Blue out

Test_B pulse = Blue out wrt Red out

Averaging the current gives a direct measure of the delay between the two edges. When A precedes B the current pulse is +50 μ A, and the output voltage goes up. When B precedes A, the pulse is -50 μ A.

For the logic to work correctly, A and B must have a period of overlap while they are high (a delay longer than the pulse width cannot be measured).

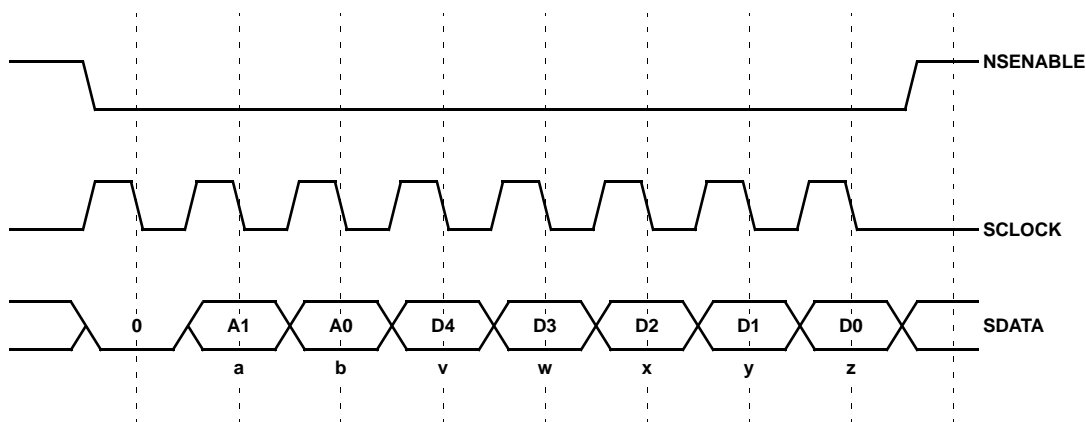


FIGURE 14.

Signals A and B are derived from the video input by comparing the video signal with a slicing level, which is set by an internal DAC. This enables the delay to be measured either from the rising edges of sync-like signals encoded on top of the video or from a dedicated set-up signal. The outputs can be used to set the correct delays for the signals received.

The DAC level is set through the serial input by bits 1 through 4 directed to the test register (00).

Test Mode

Bit zero of the test register is set to 0 for normal operation. If it is set to 1 then the device is in Test Mode. In Test Mode, the DAC voltage is directed to the Green channel output, while for the Red and Blue channels, the test outputs are now pulses of current which are generated by looking at the delay between the input and output of the channel. They thus enable the delay to be measured.

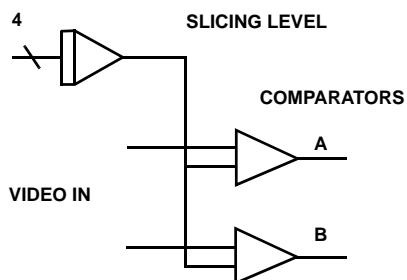
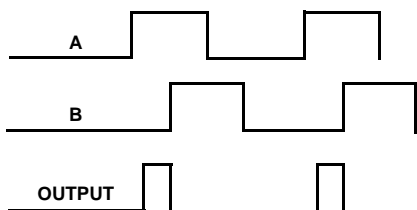
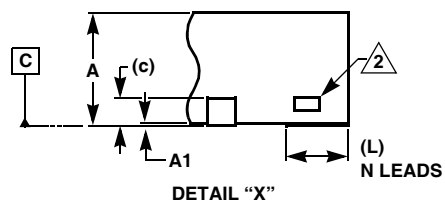
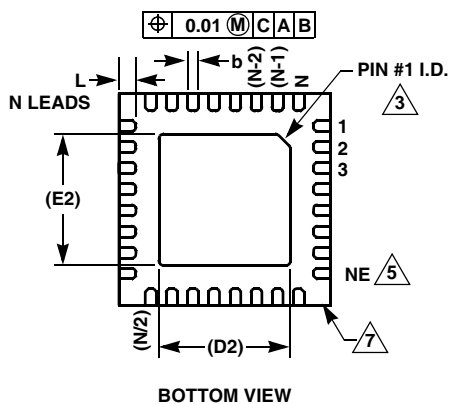
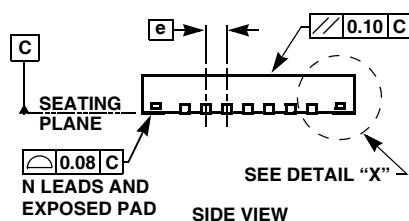
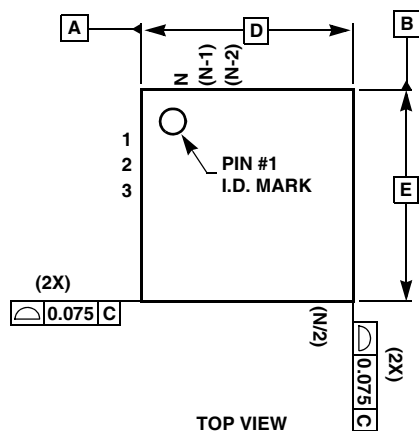


FIGURE 15. DELAY DETECTOR

TABLE 2.

| wxyz | DAC/mV |
|------|--------|
| 1000 | -400 |
| 1001 | -350 |
| 1010 | -300 |
| 1011 | -250 |
| 1100 | -200 |
| 1101 | -150 |
| 1110 | -100 |
| 1111 | -50 |
| 0000 | 0 |
| 0001 | 50 |
| 0010 | 100 |
| 0011 | 150 |
| 0100 | 200 |
| 0101 | 250 |
| 0110 | 300 |
| 0111 | 350 |

NOTE: Test Register word = 000wxyz. If t = 1 test mode else normal. wxyz fed to DAC. z is LSB

Quad Flat No-Lead Plastic Package (QFN)**L20.5x5C**

**20 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE
(COMPLIANT TO JEDEC MO-220)**

| SYMBOL | MILLIMETERS | | | NOTES |
|--------|-------------|---------|------|-------|
| | MIN | NOMINAL | MAX | |
| A | 0.80 | 0.90 | 1.00 | - |
| A1 | 0.00 | 0.02 | 0.05 | - |
| b | 0.28 | 0.30 | 0.32 | - |
| c | 0.20 REF | | | - |
| D | 5.00 BASIC | | | - |
| D2 | 3.70 REF | | | 8 |
| E | 5.00 BASIC | | | - |
| E2 | 3.70 REF | | | 8 |
| e | 0.65 BASIC | | | - |
| L | 0.35 | 0.40 | 0.45 | - |
| N | 20 | | | 4 |
| ND | 5 REF | | | 6 |
| NE | 5 REF | | | 5 |

Rev. 0 6/06

NOTES:

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Tiebar view shown is a non-functional feature.
3. Bottom-side pin #1 I.D. is a diepad chamfer as shown.
4. N is the total number of terminals on the device.
5. NE is the number of terminals on the "E" side of the package (or Y-direction).
6. ND is the number of terminals on the "D" side of the package (or X-direction). $ND = (N/2) - NE$.
7. Inward end of terminal may be square or circular in shape with radius $(b/2)$ as shown.
8. If two values are listed, multiple exposed pad options are available. Refer to device-specific datasheet.
9. One of 10 packages in MDP0046

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